

## Description

The DML3011ALFDS load switch provides a component and area-reducing solution for efficient power domain switching. In addition to integrated control functionality with ultra-low on-resistance, this device offers system safeguards and adjustable Slew Rate control signaling. This cost effective solution is ideal for power management and hot-swap applications requiring low power consumption in a small footprint.

## Features and Benefits

- Advanced Controller with Charge Pump
- Integrated N-Channel MOSFET with Ultra Low  $R_{ON}$
- Input Voltage Range 0.5V to 20V
- Adjustable Soft-Start via Controlled Slew Rate
- Thermal Shutdown
- V<sub>CC</sub> Undervoltage Lockout
- Short-Circuit Protection
- Extremely Low Standby Current
- Load Bleed (Quick Discharge)
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative. <https://www.diodes.com/quality/product-definitions/>**

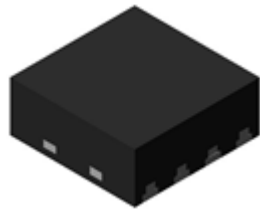
## Applications

- Portable electronics and systems
- Notebooks and tablet computers
- Telecom, networking, medical, and industrial equipment
- Set-top boxes, servers, and gateways
- Hot-swap devices and peripheral ports

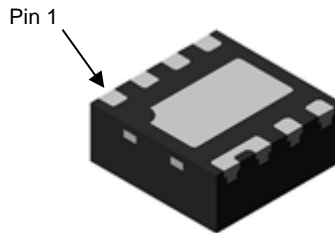
## Mechanical Data

- Package: V-DFN2020-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.011 grams (Approximate)

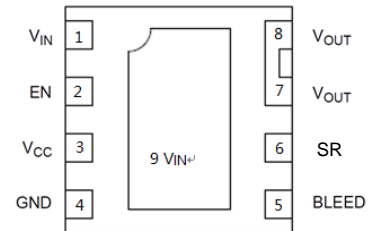
V-DFN2020-8 (Type N)



Top View



Bottom View



Top View

## Ordering Information (Note 4)

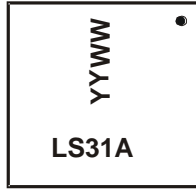
Part Number	Package	Packing	
		Qty.	Carrier
DML3011ALFDS-7	V-DFN2020-8 (Type N)	3,000	Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**

Site 1

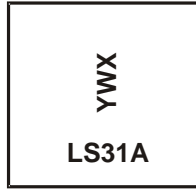
V-DFN2020-8 (Type N)



LS31A = Product Type Marking Code  
 YYWW = Date Code Marking  
 YY = Last Two Digits of Year (ex: 24 = 2024)  
 WW = Week Code (01 to 53)

Site 2

V-DFN2020-8 (Type N)

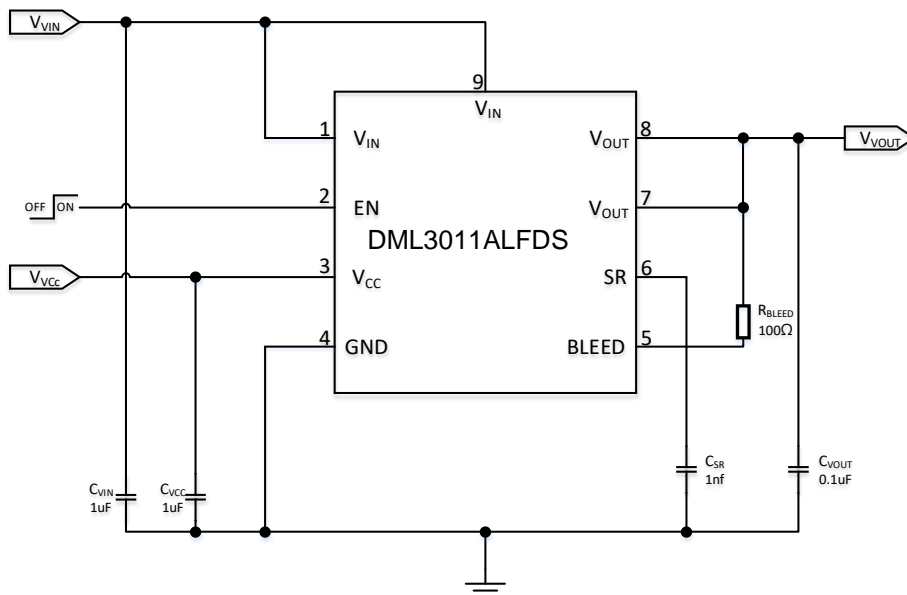


LS31A = Product Type Marking Code  
 YWX = Date Code Marking  
 Y = Year (ex: 4 = 2024)  
 W = Week (ex: a = Week 27; z Represents Week 52 and 53)  
 X = Internal Code (ex: U = Monday)

Date Code Key

<b>Year</b>	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034
<b>Code</b>	3	4	5	6	7	8	9	0	1	2	3	4
<b>Week</b>	1-26			27-52			53					
<b>Code</b>	A-Z			a-z			z					
<b>Internal Code</b>	Sun	Mon	Tue	Wed	Thu	Fri	Sat					
<b>Code</b>	T	U	V	W	X	Y	Z					

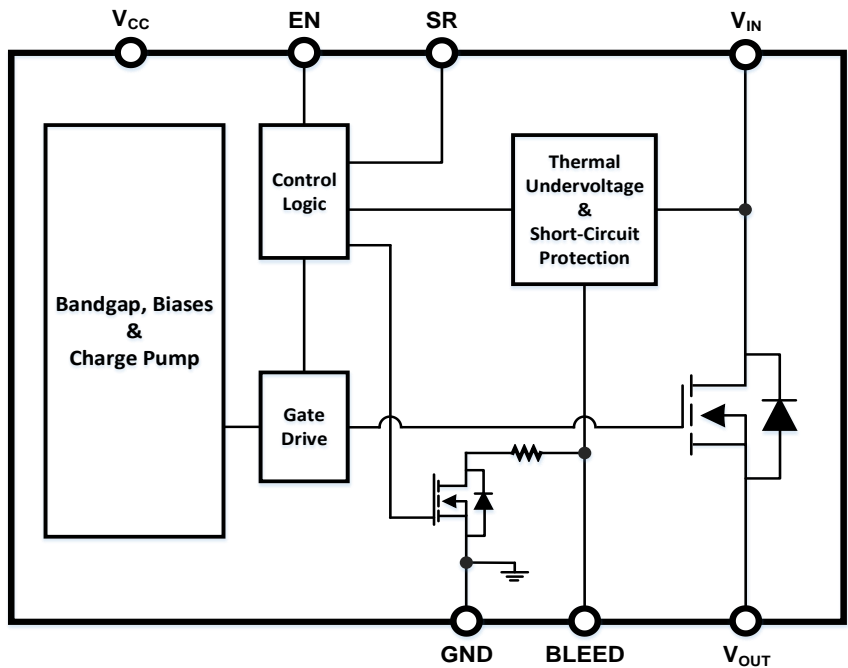
**Typical Application Circuit**



### Pin Description

Pin Number	Pin Name	Pin Function
1, 9	V <sub>IN</sub>	Drain of internal MOSFET, Pin 1 must connect to Pin 9.
2	EN	Active-high digital input used to turn on the MOSFET, pin has an internal pulldown resistor to GND.
3	V <sub>CC</sub>	Supply voltage to controller (3.0V to 5.5V)
4	GND	Controller ground
5	BLEED	Load bleed connection, must be tied to V <sub>OUT</sub> through a resistor ≤ 1kΩ.
6	SR	Slew rate adjustment
7, 8	V <sub>OUT</sub>	Source of internal MOSFET connected to load

### Function Block Diagram



### Absolute Maximum Rating

Parameter	Rating
V <sub>IN</sub> , BLEED, V <sub>OUT</sub> to GND	-0.3V to 24V
EN, V <sub>CC</sub> , SR to GND	-0.3V to 6V
I <sub>MAX</sub> *	10.5A
Storage Temperature (T <sub>s</sub> )	-65°C to +150°C

### Recommended Operating Ranges

Parameter	Rating
Supply Voltage (V <sub>CC</sub> )	3V to 5.5V
Input Voltage (V <sub>IN</sub> )	0.5V to 20V
Ambient Temperature (T <sub>A</sub> )	-40°C to +85°C
Junction Temperature (T <sub>J</sub> )	-40°C to +125°C
Package Thermal Resistance (θ <sub>JC</sub> )	5.3°C/W
Package Thermal Resistance (θ <sub>JA</sub> )	40°C/W

\*I<sub>MAX</sub> defined as the maximum steady state current the load switch can pass at room ambient temperature without entering thermal lockout.

### Electrical Characteristics

(T<sub>A</sub> = +25°C, V<sub>VCC</sub> = 3.3V, V<sub>VIN</sub> = 5V, C<sub>VIN</sub> = 1μF, C<sub>VOUT</sub> = 0.1μF, C<sub>VCC</sub> = 1μF, C<sub>SR</sub> = 1nF, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>IN</sub>	Input Voltage	—	0.5	—	20	V
V <sub>CC</sub>	Supply Voltage	—	3.0	—	5.5	V
I <sub>DYN</sub>	V <sub>CC</sub> Dynamic Supply Current	V <sub>EN</sub> = V <sub>CC</sub> = 3V, V <sub>IN</sub> = 20V	—	150	290	μA
		V <sub>EN</sub> = V <sub>CC</sub> = 5.5V, V <sub>IN</sub> = 1.8V	—	200	390	μA
I <sub>STBY</sub>	V <sub>CC</sub> Shutdown Supply Current	V <sub>CC</sub> = 3V, V <sub>EN</sub> = 0V	—	0.1	1	μA
		V <sub>CC</sub> = 5.5V, V <sub>EN</sub> = 0V	—	0.1	2	μA
V <sub>ENH</sub>	EN High Level Voltage	V <sub>CC</sub> = 3V to 5.5V	2.0	—	—	V
V <sub>ENL</sub>	EN Low Level Voltage	V <sub>CC</sub> = 3V to 5.5V	—	—	0.8	V
R <sub>BLEED</sub>	Bleed Resistance	V <sub>CC</sub> = 3V, V <sub>EN</sub> = 0V	90	120	180	Ω
		V <sub>CC</sub> = 5.5V, V <sub>EN</sub> = 0V	70	100	130	Ω
I <sub>BLEED</sub>	Bleed Pin Leakage Current	V <sub>CC</sub> = V <sub>EN</sub> = 3V, V <sub>IN</sub> = 1.8V	—	3	—	μA
		V <sub>CC</sub> = V <sub>EN</sub> = 3V, V <sub>IN</sub> = 20V	—	32	—	μA
<b>Switching Device</b>						
R <sub>ON</sub>	Switch On-State Resistance	V <sub>CC</sub> = 3.3V, V <sub>IN</sub> = 1.8V	—	10	12.5	mΩ
		V <sub>CC</sub> = 3.3V, V <sub>IN</sub> = 5V	—	10	12.5	mΩ
		V <sub>CC</sub> = 3.3V, V <sub>IN</sub> = 12V	—	10	12.5	mΩ
		V <sub>CC</sub> = 5V, V <sub>IN</sub> = 1.8V	—	7.5	10.5	mΩ
		V <sub>CC</sub> = 5V, V <sub>IN</sub> = 5V	—	7.5	10.5	mΩ
		V <sub>CC</sub> = 5V, V <sub>IN</sub> = 12V	—	7.5	10.5	mΩ
I <sub>LEAK</sub>	Input Shutdown Supply Current	V <sub>EN</sub> = 0V, V <sub>IN</sub> = 20V	—	—	10	μA
R <sub>PDEN</sub>	EN Pulldown Resistance	—	70	100	130	kΩ
<b>Fault Protection</b>						
T <sub>OTP</sub>	Thermal Shutdown Threshold	V <sub>CC</sub> = 3V to 5.5V	—	+145	—	°C
T <sub>OTPHYS</sub>	Thermal Shutdown Hysteresis	V <sub>CC</sub> = 3V to 5.5V	—	+20	—	°C
V <sub>UVLO</sub>	V <sub>CC</sub> Lockout Threshold	—	2.3	2.55	2.8	V
V <sub>UVLOHYS</sub>	V <sub>CC</sub> Lockout Hysteresis	—	—	200	—	mV
V <sub>SCP</sub>	Short-Circuit Protection Threshold	V <sub>CC</sub> = 3.3V, V <sub>IN</sub> = 0.5V	140	240	350	mV
		V <sub>CC</sub> = 3.3V, V <sub>IN</sub> = 1.2V to 12V	120	240	500	mV
		V <sub>CC</sub> = 3.3V, V <sub>IN</sub> = 20V	100	250	500	mV

**Switching Characteristics**

( $T_A = +25^\circ\text{C}$ ,  $V_{\text{TERM}} = V_{\text{CC}} = 5\text{V}$ ,  $C_{\text{SR}} = \text{floating}$ ,  $R_{\text{VOUT}} = 10\Omega$ ,  $C_{\text{VIN}} = 1\mu\text{F}$ ,  $C_{\text{VOUT}} = 0.1\mu\text{F}$ ,  $C_{\text{VCC}} = 1\mu\text{F}$ , unless otherwise specified.)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b><math>V_{\text{IN}} = 1.8\text{V}</math></b>						
$t_{\text{ON}}$	Output Turn-On Delay Time	$V_{\text{CC}} = 3.3\text{V}$	100	350	600	$\mu\text{s}$
		$V_{\text{CC}} = 5\text{V}$	60	220	400	
$t_{\text{OFF}}$	Output Turn-Off Delay Time	$V_{\text{CC}} = 3.3\text{V}$	—	1	2	$\mu\text{s}$
		$V_{\text{CC}} = 5\text{V}$	—	1	2	
SR	Output Slew Rate	$V_{\text{CC}} = 3.3\text{V}$	1	10	20	kV/s
		$V_{\text{CC}} = 5\text{V}$	1	10	20	
<b><math>V_{\text{IN}} = 12\text{V}</math></b>						
$t_{\text{ON}}$	Output Turn-On Delay Time	$V_{\text{CC}} = 3.3\text{V}$	100	300	600	$\mu\text{s}$
		$V_{\text{CC}} = 5\text{V}$	60	170	400	
$t_{\text{OFF}}$	Output Turn-Off Delay Time	$V_{\text{CC}} = 3.3\text{V}$	—	1	2	$\mu\text{s}$
		$V_{\text{CC}} = 5\text{V}$	—	1	2	
SR	Output Slew Rate	$V_{\text{CC}} = 3.3\text{V}$	5	20	40	kV/s
		$V_{\text{CC}} = 5\text{V}$	5	20	40	

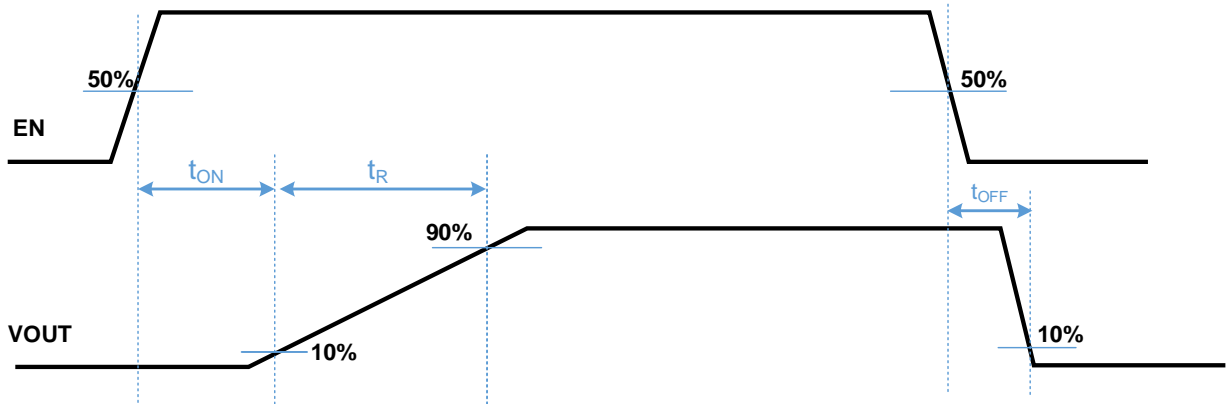
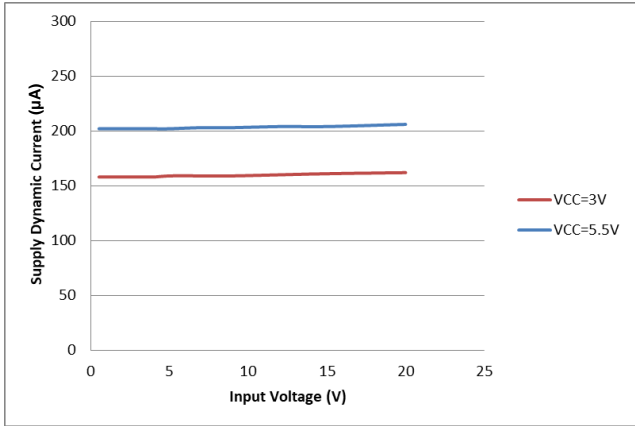


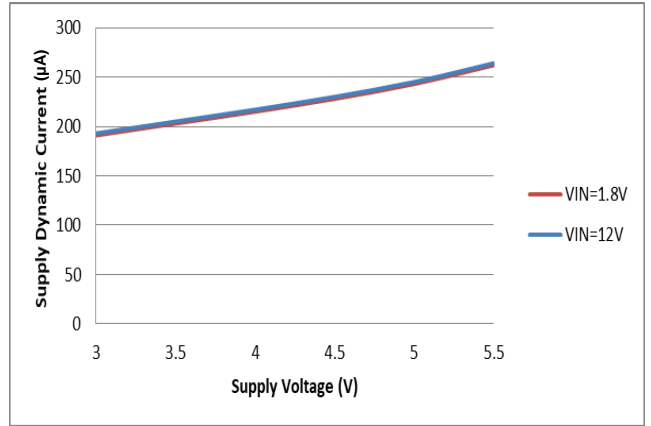
Figure 1. Timing Diagram

**Performance Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

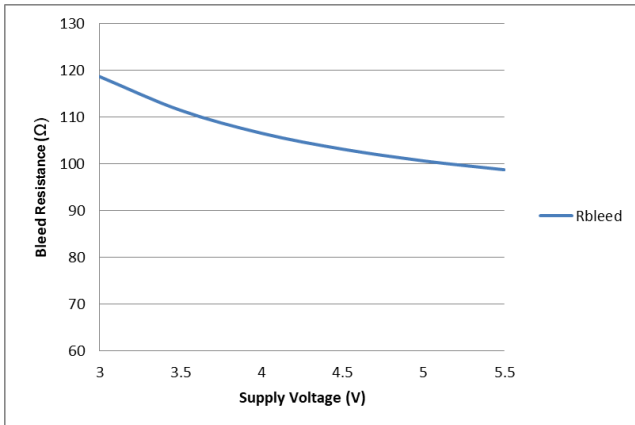
**Supply Dynamic Current vs. Input Voltage**



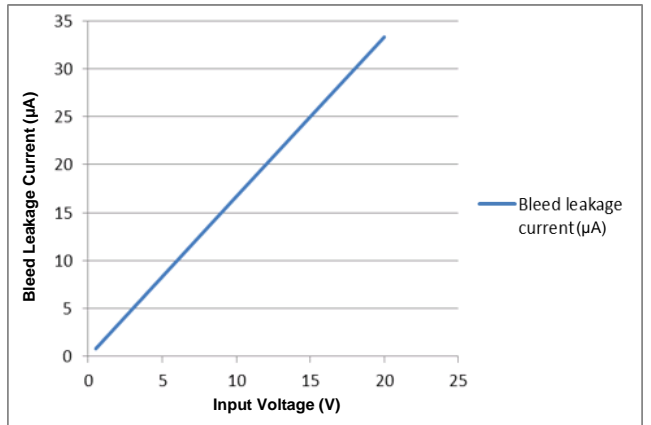
**Supply Dynamic Current vs. Supply Voltage**



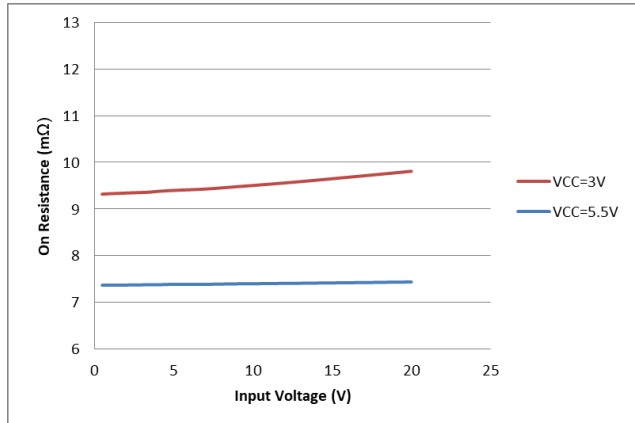
**Bleed Resistance vs. Supply Voltage**



**Bleed Leakage Current vs. Input Voltage**



**ON Resistance vs. Input Voltage**



**Performance Characteristics (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.) (continued)**

**Turn ON Response**

$V_{IN} = 1.8\text{V}$ ,  $V_{CC} = 3.3\text{V}$ ,  $V_{EN} = 0\text{V}$  to  $3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



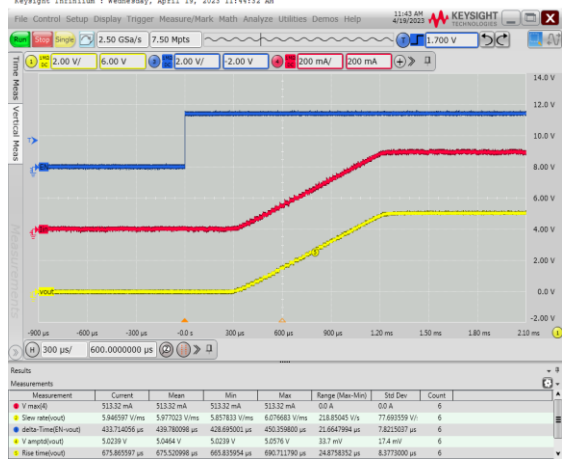
**Turn OFF Response**

$V_{IN} = 1.8\text{V}$ ,  $V_{CC} = 3.3\text{V}$ ,  $V_{EN} = 0\text{V}$  to  $3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



**Turn ON Response**

$V_{IN} = 5\text{V}$ ,  $V_{CC} = 3.3\text{V}$ ,  $V_{EN} = 0\text{V}$  to  $3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



**Turn OFF Response**

$V_{IN} = 5\text{V}$ ,  $V_{CC} = 3.3\text{V}$ ,  $V_{EN} = 0\text{V}$  to  $3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



**Turn ON Response**

$V_{IN} = 12\text{V}$ ,  $V_{CC} = 3.3\text{V}$ ,  $V_{EN} = 0\text{V}$  to  $3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



**Turn OFF Response**

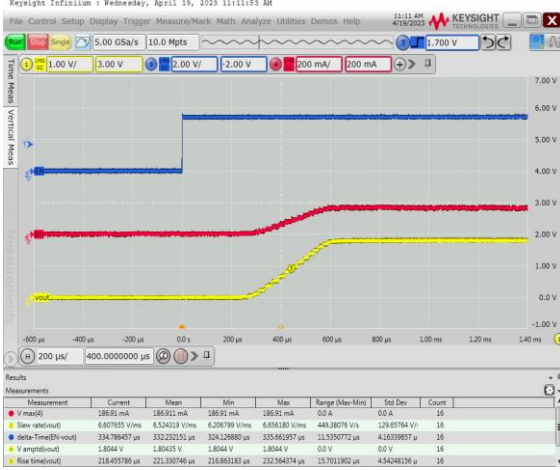
$V_{IN} = 12\text{V}$ ,  $V_{CC} = 3.3\text{V}$ ,  $V_{EN} = 0\text{V}$  to  $3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



**Performance Characteristics (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.) (continued)**

**Turn ON Response**

$V_{IN} = 1.8\text{V}$ ,  $V_{VCC} = 5\text{V}$ ,  $V_{EN} = 0\text{V to } 3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



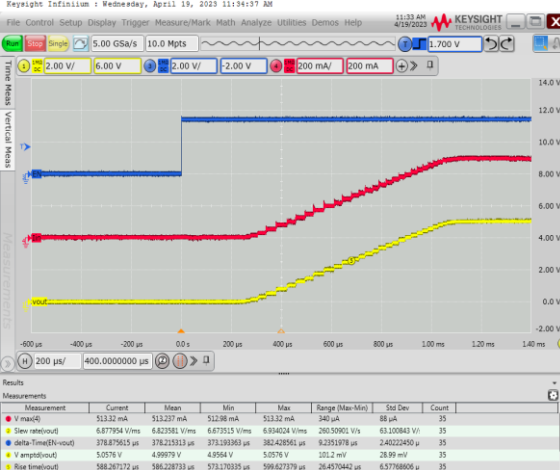
**Turn OFF Response**

$V_{IN} = 1.8\text{V}$ ,  $V_{VCC} = 5\text{V}$ ,  $V_{EN} = 0\text{V to } 3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



**Turn ON Response**

$V_{IN} = 5\text{V}$ ,  $V_{VCC} = 5\text{V}$ ,  $V_{EN} = 0\text{V to } 3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



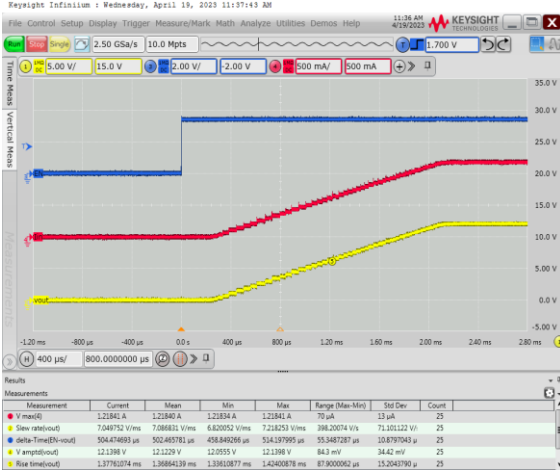
**Turn OFF Response**

$V_{IN} = 5\text{V}$ ,  $V_{VCC} = 5\text{V}$ ,  $V_{EN} = 0\text{V to } 3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



**Turn ON Response**

$V_{IN} = 12\text{V}$ ,  $V_{VCC} = 5\text{V}$ ,  $V_{EN} = 0\text{V to } 3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$



**Turn OFF Response**

$V_{IN} = 12\text{V}$ ,  $V_{VCC} = 5\text{V}$ ,  $V_{EN} = 0\text{V to } 3.3\text{V}$ ,  $C_{SR} = 1\text{nF}$ ,  $R_L = 10\Omega$





## Application Information

### General Description

The DML3011ALFDS is a single channel load switch with a controlled adjustable turn-on in an 8-pin V-DFN2020-8 (Type N) package. The device contains an n-channel MOSFET that can operate over an input voltage range of 0.5V to 20V and can support a maximum continuous current of 10.5A. The wide input voltage range and high current capability enable the device to be used across multiple designs and end equipment. 10mΩ on-resistance minimizes the voltage drop across the load switch and power loss from the load switch.

During shutdown, the device has very low leakage current, thereby reducing unnecessary leakages for downstream modules during standby. The DML3011ALFDS also has 100Ω on-chip resistor embedded on BLEED pin for quick discharge of the output when switch is disabled.

### Enable Control

The DML3011ALFDS allows for enabling the MOSFET in an active-high configuration. When the V<sub>CC</sub> supply pin has an adequate voltage applied and the EN pin is at logic high level, the MOSFET will be enabled. Similarly, when the EN pin is at logic low level, the MOSFET will be disabled. An internal pulldown resistor to ground on the EN pin ensures that the MOSFET will be disabled when not being driven.

### Power Sequencing

The DML3011ALFDS functions with fixed power sequence, the performance of output turn-on delay may vary from what is specified. To achieve the specified performance, recommended power sequences are:

- 1.) V<sub>CC</sub> → V<sub>IN</sub> → V<sub>EN</sub>
- 2.) V<sub>IN</sub> → V<sub>CC</sub> → V<sub>EN</sub>

### Load Bleed (Quick Discharge)

The DML3011ALFDS has an internal bleed discharge device, which is used to bleed the charge off from the load to ground after the MOSFET is disabled. The bleed discharge device is enabled whenever the MOSFET is disabled. The MOSFET and the bleed device are never concurrently active.

The BLEED pin must be connected to V<sub>OUT</sub> either directly or through an external resistor, R<sub>EXT</sub>. R<sub>EXT</sub> should not exceed 1kΩ and can be used to increase the total bleed resistance.

To ensure that the power dissipated across R<sub>BLEED</sub> is kept at safe level, dissipated power of R<sub>BLEED</sub> needs to be detailedly calculated. The maximum continuous power that can be dissipated across R<sub>BLEED</sub> is 0.4W. R<sub>EXT</sub> can be used to decrease the amount of power dissipated across R<sub>BLEED</sub>.

### Adjustable Rise Time (Slew Rate Control)

The DML3011ALFDS has controlled rise time for inrush current control. A capacitor to ground on the SR pin adjusts the rise time. Without a capacitor on SR, the rise time is at its minimum for fastest timing. An approximate equation for the relationship between C<sub>SR</sub>, V<sub>VIN</sub>, and rise time when V<sub>CC</sub> is set to 5V is shown in Equation 1. As shown in Figure 1, rise time is defined as from 10% to 90% measurement on V<sub>OUT</sub>.

$$t_R = K1 \times ((C_{SR} \times K2) \times V_{VIN}) / I_{SR}$$

Where: K1 = 0.06 and K2 = 0.3

C<sub>SR</sub> is the ramp-up control setting capacitor in nF

I<sub>SR</sub> = 0.5μA is SR pin output current

t<sub>R</sub> is the total ramp time in ms

Table 1 contains rise time values measured on a typical device. Rise times shown below are only valid for the power-up sequence 1.

**Table 1. Rise Time vs. SR Capacitor**

C <sub>SR</sub>	Rise Time (ms)				
	V <sub>CC</sub> = 5V, C <sub>L</sub> = 0.1μF, R <sub>L</sub> = 10Ω, +25°C; Measure V <sub>OUT</sub> rising time from 10% to 90% V <sub>VIN</sub>				
	V <sub>VIN</sub> = 20V	V <sub>VIN</sub> = 12V	V <sub>VIN</sub> = 5V	V <sub>VIN</sub> = 3.3V	V <sub>VIN</sub> = 1.8V
0 (floating)	0.5	0.38	0.24	0.2	0.14
0.22nF	0.5	0.38	0.24	0.2	0.14
0.47nF	1.05	0.63	0.26	0.2	0.14
1nF	2.33	1.37	0.6	0.4	0.22
2.2nF	5.23	3.02	1.34	0.92	0.51
4.7nF	11.66	6.54	2.86	1.85	1.18
10nF	23.16	13.84	5.79	3.96	2.25

Note: An SR capacitor less than 47nF for system success startup recommended.

## Application Information (continued)

### Short-Circuit Protection

The DML3011ALFDS is equipped with short-circuit protection that is used to help protect the part and the system from a sudden high-current event, such as the output,  $V_{OUT}$ , being shorted to ground. This circuitry is only active when the gate of MOSFET is fully charged.

Once active, the circuitry monitors the difference in the voltage on the  $V_{IN}$  pin and the voltage on the BLEED pin. In order for the  $V_{OUT}$  voltage to be monitored through the BLEED pin, it is required that BLEED pin be connected to  $V_{OUT}$  either directly or through a resistor,  $R_{EXT}$ , which should not exceed 1k $\Omega$ . With the BLEED pin connected to  $V_{OUT}$ , the short-circuit protection is able to monitor the voltage drop across the MOSFET.

If the voltage drop across the MOSFET is greater than or equal to the short-circuit protection threshold voltage, the MOSFET is turned off immediately and the load bleed is activated. The part remains latched in this off state until EN is toggled or  $V_{CC}$  supply voltage is cycled, at which point the MOSFET will be turn-on delay and slew rate. The current through the MOSFET that will cause a short-circuit event can be calculated by dividing the short-circuit protection threshold by expected on-resistance of the MOSFET.

### Thermal Shutdown

The DML3011ALFDS is equipped with thermal shutdown protection for internal or externally generated excessive temperatures. This circuitry is disabled when EN is not active to reduce standby current. When an overtemperature condition is detected, the MOSFET is turned off immediately and the load bleed is active.

The part comes out of thermal shutdown when the junction temperature decreases to a safe operating temperature as dictated by the thermal hysteresis. Upon exiting a thermal shutdown state, and if EN remains active, the MOSFET will be turned on in a controlled fashion with the normal output turn-on delay and slew rate.

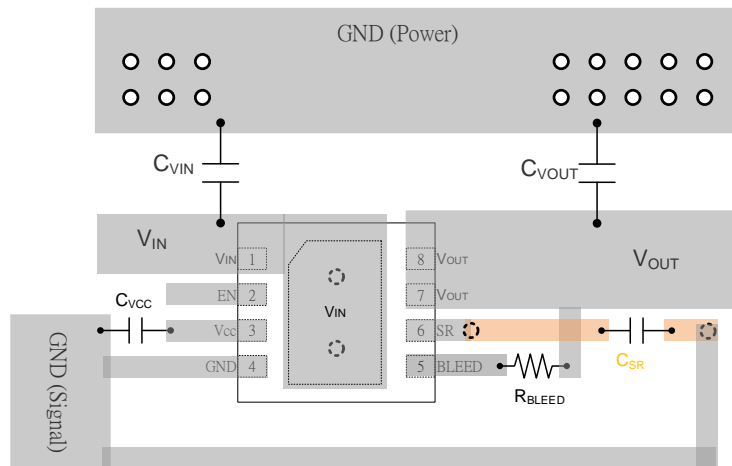
### Undervoltage Lockout

The DML3011ALFDS is equipped with undervoltage lockout protection. DML3011ALFDS turns the MOSFET off and activates the load bleed when the input voltage  $V_{CC}$  is less than or equal to the undervoltage lockout threshold. This circuitry is disabled when EN is not active to reduce standby current.

If the  $V_{CC}$  voltage rises above the undervoltage lockout threshold and EN remains active, the MOSFET will be turned on in a controlled fashion with the normal output turn-on delay and slew rate.

### PCB Layout Consideration

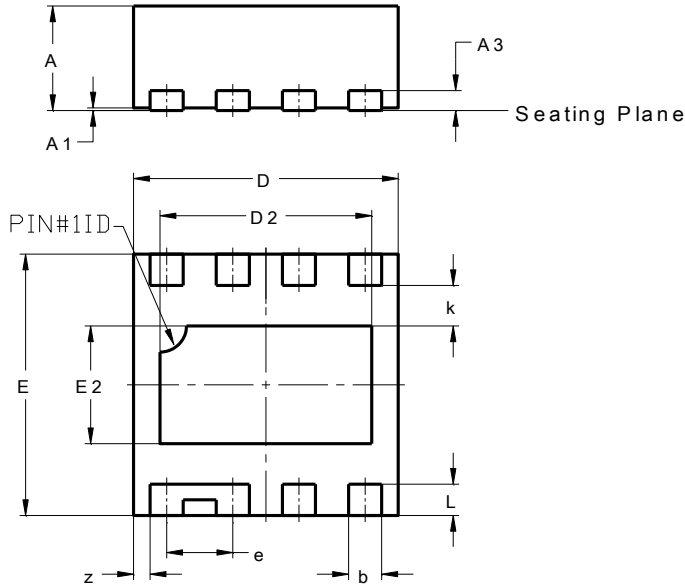
1. Place the input/output capacitors  $C_{VIN}$  and  $C_{VOUT}$  as close as possible to the  $V_{IN}$  and  $V_{OUT}$  pins.
2. The power traces which are  $V_{IN}$  trace,  $V_{OUT}$  trace and GND trace should be short, wide and directly for minimizing parasitic inductance.
3. Place feedback resistance  $R_{BLEED}$  as close as possible to BLEED pin.
4. Place  $C_{VCC}$  capacitor near the device pin.
5. Connect the signal ground to the GND pin, and keep a single connection from GND pin to the power ground behind the input or output capacitors.
6. For better power dissipation, via holes are recommended to connect the exposed pad's landing area to a large copper polygon on the other side of the printed circuit board. The copper polygons and exposed pad shall connect to  $V_{IN}$  pin on the printed circuit board.



**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**V-DFN2020-8 (Type N)**

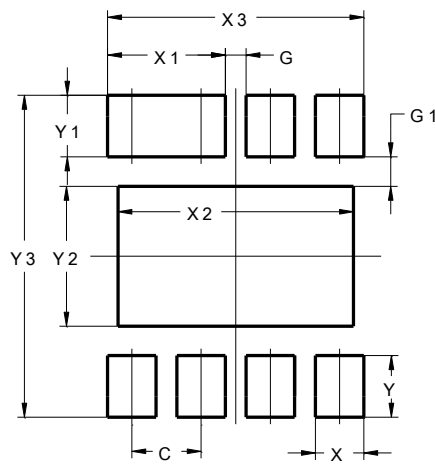


V-DFN2020-8 (Type N)			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	--	--	0.152
b	0.20	0.30	0.25
D	1.95	2.05	2.00
D2	1.50	1.70	1.60
E	1.95	2.05	2.00
E2	0.80	1.00	0.90
e	--	--	0.50
k	--	--	0.31
L	0.19	0.29	0.24
z	--	--	0.125
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**V-DFN2020-8 (Type N)**



Dimensions	Value (in mm)
C	0.500
G	0.150
G1	0.210
X	0.350
X1	0.850
X2	1.700
X3	1.850
Y	0.440
Y1	0.440
Y2	1.000
Y3	2.300

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